

# Continuous Alloy Innovation

## Over 200 Alloys Available

High-reliability alloys available for InFORMS®, preforms, and solder pastes



- Indalloy®51E (GalInSn)
- Indalloy®60 (GalIn)
- Indalloy®77 (GalIn)
- Indalloy®300E (GalIn)

Liquid Metal  
for Thermal  
Interface  
<30°C



Low-Temperature  
Soldering and  
Sealing  
30–210°C



- Indalloy®1E (InSn)
- Indalloy®4 (In)
- Indalloy®38 (BiPbSn)
- Indalloy®117 (BiPbInSnCd)
- Indalloy®227 (SnInAg)
- Indalloy®254 (SnInAg)
- Indalloy®281 (BiSn)
- Indalloy®282 (BiSnAg)
- Durafuse® LT
- Indalloy®301LT

- Indalloy®100 (SnPbAg)
- Indalloy®106 (Sn63)
- Indalloy®121 (SnAg)
- Indalloy®241 (SAC387)
- Indalloy®256 (SAC305)
- Indalloy®276 (SnAg+)
- Indalloy®291 (SnCu+)
- Durafuse® HR

Traditional  
Soldering  
150–260°C



- Indalloy®133 (SnSb)
- Indalloy®228 (Sn10)
- Indalloy®266 (HMP)
- Indalloy®292
- Durafuse® HT

High-Temperature  
Soldering  
230–360°C



- Indalloy®182 (AuSn)
- Indalloy®183 (AuGe)
- Indalloy®193 (AgCu)
- Indalloy®200 (Au)

Au and Braze  
Alloys  
>280°C



Learn more: [www.indium.com/solder-alloys](http://www.indium.com/solder-alloys) Contact our engineers: [askus@indium.com](mailto:askus@indium.com)

### From One Engineer To Another®

All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.



# Innovative Alloy Technologies

Available for InFORMS<sup>®</sup>, preforms, and solder pastes



Improves Drop Shock Resistance

## Durafuse<sup>®</sup> LT

Innovative Low-Temperature Alloy Technology

- Two orders of magnitude better drop shock performance compared to Bi-containing low-temperature options
- Energy consumption reduced by 15%
- Enables complex processes and designs, such as step soldering, large temperature gradients, and fine feature printing
- Superior thermal cycling performance for fine-pitch and wafer-level CSP components

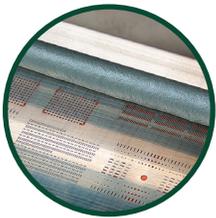


High-Performance Solder Preforms

## Indalloy<sup>®</sup> 276

Improved Reliability for Power Electronics Substrate-Attach

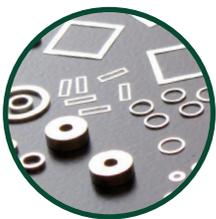
- Added Ag and Sb enables higher operating temperatures
- Compatible with InFORMS<sup>®</sup> technology



High-Reliability Automotive Alloy

## Durafuse<sup>®</sup> HR

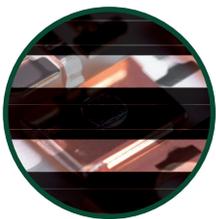
- Outstanding -40°C/125°C and -40°C/150°C and thermal cycling performance through 3,000+ cycles
- Lowest voiding high-reliability alloy system



High-Reliability Alloy

## Indalloy<sup>®</sup> 133

- Proven higher temperature alloy
- Improved reliability over other common Sn-based alloys
- Excellent solderability and wetting
- Compatible with InFORMS<sup>®</sup> technology



Proven Fast Sintering

## QuickSinter<sup>®</sup>

Silver Sintering Paste

- >3 dots/second—consistent high-speed dispensing
- Controllable bondline thickness from 30–70µm
- Excellent joint strength
- Versatile sintering profiles
- Pressureless sintering solution with pressurized sintering capabilities
- Porosity: <30%\*
- Voiding: <1%\*

*\*Average on most application runs*

Learn more: [www.indium.com/solder-alloys](http://www.indium.com/solder-alloys)

Contact our engineers: [askus@indium.com](mailto:askus@indium.com)

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